Features

- Fast Read Access Time – 55 ns
- Low Power CMOS Operation
  - 100 µA Maximum Standby
  - 40 mA Maximum Active at 5 MHz
- JEDEC Standard Packages
  - 40-lead PDIP
  - 44-lead PLCC
  - 40-lead VSOP
- Direct Upgrade from 512-Kbit, 1-Mbit, and 2-Mbit (AT27C516, AT27C1024, and AT27C2048) EPROMs
- 5V ± 10% Power Supply
- High Reliability CMOS Technology
  - 2,000V ESD Protection
  - 200 mA Latchup Immunity
- Rapid Programming Algorithm – 50 µs/Word (Typical)
- CMOS and TTL Compatible Inputs and Outputs
- Integrated Product Identification Code
- Industrial Temperature Range
- Green (Pb/Halide-free) Packaging Option

4-Megabit (256K x 16) OTP EPROM

AT27C4096

1. Description

The AT27C4096 is a low-power, high-performance 4,194,304-bit one-time programmable read-only memory (OTP EPROM) organized 256K by 16 bits. It requires a single 5V power supply in normal read mode operation. Any word can be accessed in less than 55 ns, eliminating the need for speed-reducing WAIT states. The x16 organization makes this part ideal for high-performance 16- and 32-bit microprocessor systems.

In read mode, the AT27C4096 typically consumes 15 mA. Standby mode supply current is typically less than 10 µA.

The AT27C4096 is available in industry-standard JEDEC-approved one-time programmable (OTP) plastic PDIP, PLCC, and VSOP packages. The device features two-line control ($\overline{CE}$, $\overline{OE}$) to eliminate bus contention in high-speed systems.

With high density 256K word storage capability, the AT27C4096 allows firmware to be stored reliably and to be accessed by the system without the delays of mass storage media.

Atmel's AT27C4096 has additional features that ensure high quality and efficient production use. The Rapid Programming Algorithm reduces the time required to program the part and guarantees reliable programming. Programming time is typically only 50 µs/word. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry-standard programming equipment to select the proper programming algorithms and voltages.

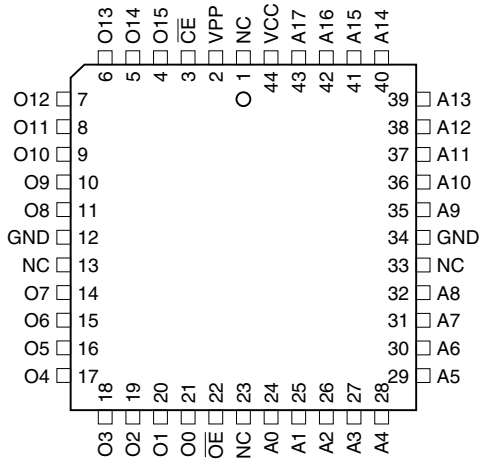
0311I–EPROM–12/07

2. Pin Configurations

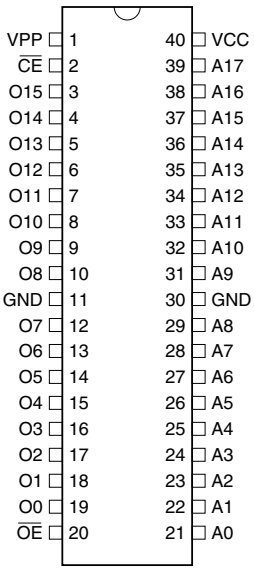
Pin Name	Function
A0 - A17	Addresses
O0 - O15	Outputs
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
NC	No Connect

Note: Both GND pins must be connected.

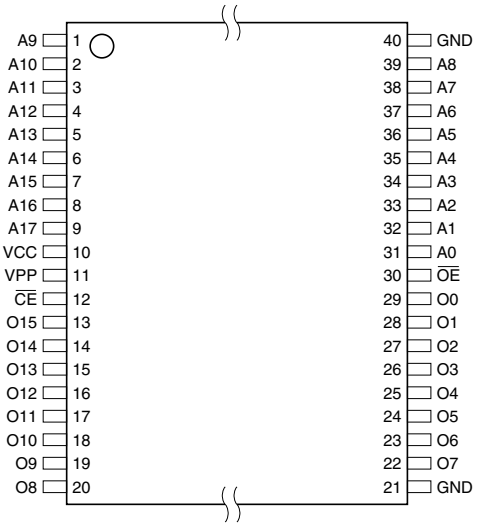
2.1 44-lead PLCC Top View



2.2 40-lead PDIP Top View



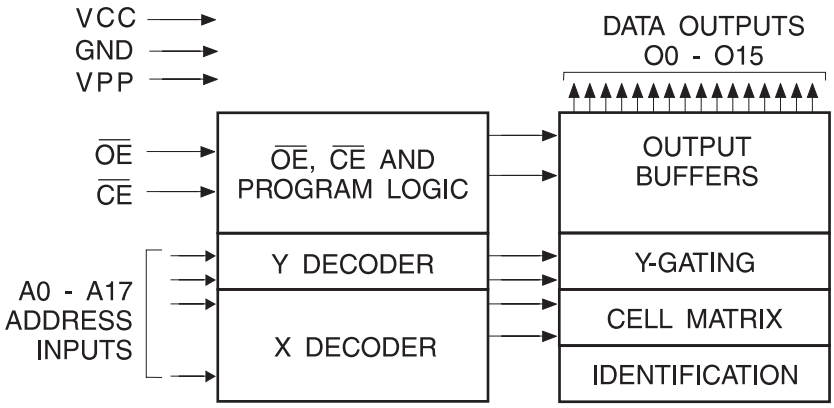
2.3 40-lead VSOP (Type 1) Top View



3. System Considerations

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed datasheet limits, resulting in device non-conformance. At a minimum, a 0.1 µF high frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the V_{CC} and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a 4.7 µF bulk electrolytic capacitor should be utilized, again connected between the V_{CC} and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

4. Block Diagram



5. Absolute Maximum Ratings*

Temperature Under Bias	-55° C to +125° C
Storage Temperature	-65° C to +150° C
Voltage on Any Pin with Respect to Ground	-2.0V to +7.0V(1)
Voltage on A9 with Respect to Ground	-2.0V to +14.0V(1)
V_{PP} Supply Voltage with Respect to Ground	-2.0V to +14.0V(1)

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: 1. Maximum voltage is -0.6V DC which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is V_{CC} + 0.75V DC which may overshoot to +7.0V for pulses of less than 20 ns.

6. Operating Modes

Mode/Pin	$\overline{CE}$	$\overline{OE}$	Ai	V_{PP}	Outputs
Read	V_{IL}	V_{IL}	Ai	X[1]	D_{OUT}
Output Disable	X	V_{IH}	X	X	High Z
Standby	V_{IH}	X	X	X[5]	High Z
Rapid Program[2]	V_{IL}	V_{IH}	Ai	V_{PP}	D_{IN}
PGM Verify	V_{IH}	V_{IL}	Ai	V_{PP}	D_{OUT}
PGM Inhibit	V_{IH}	V_{IH}	X	V_{PP}	High Z
Product Identification[4]	V_{IL}	V_{IL}	A9 = V_H[3] A0 = V_{IH} or V_{IL} A1 - A17 = V_{IL}	V_{CC}	Identification Code

Notes:
1. X can be V_{IL} or V_{IH}.
2. Refer to the Programming characteristics.
3. V_H = 12.0 ±0.5V.
4. Two identifier words may be selected. All Ai inputs are held low (V_{IL}), except A9, which is set to V_H, and A0, which is toggled low (V_{IL}) to select the Manufacturer's Identification word and high (V_{IH}) to select the Device Code word.
5. Standby V_{CC} current (I_{SB}) is specified with $V_{PP} = V_{CC}$. $V_{CC} > V_{PP}$ will cause a slight increase in I_{SB}.

7. DC and AC Operating Conditions for Read Operation

	AT27C4096	
	-55	-90
Industrial Operating Temperature (Case)	-40° C - 85° C	-40° C - 85° C
V_{CC} Power Supply	5V ± 10%	5V ± 10%

8. DC and Operating Characteristics for Read Operation

Symbol	Parameter	Condition	Min	Max	Units
I_{LI}	Input Load Current	V_{IN} = 0V to V_{CC}		±1	µA
I_{LO}	Output Leakage Current	V_{OUT} = 0V to V_{CC}		±5	µA
I_{PP1}[2]	V_{PP}[1] Read/Standby Current	$V_{PP} = V_{CC}$		10	µA
I_{SB}	V_{CC}[1] Standby Current	I_{SB1} (CMOS) $\overline{CE}$ = V_{CC} ± 0.3V		100	µA
		I_{SB2} (TTL) $\overline{CE}$ = 2.0 to V_{CC} + 0.5V		1	mA
I_{CC}	V_{CC} Active Current	f = 5 MHz, I_{OUT} = 0 mA, $\overline{CE}$ = V_{IL}		40	mA
V_{IL}	Input Low Voltage		-0.6	0.8	V
V_{IH}	Input High Voltage		2.0	V_{CC} + 0.5	V
V_{OL}	Output Low Voltage	I_{OL} = 2.1 mA		0.4	V
V_{OH}	Output High Voltage	I_{OH} = -400 µA	2.4		V

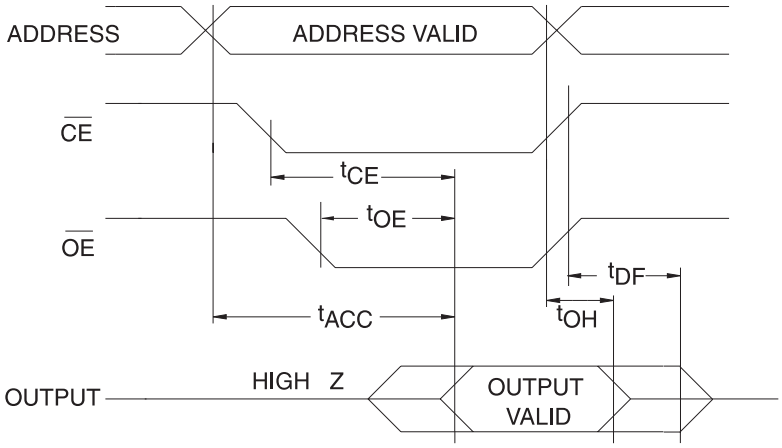
Notes:
1. V_{CC} must be applied simultaneously or before V_{PP}, and removed simultaneously or after V_{PP}
2. V_{PP} may be connected directly to V_{CC}, except during programming. The supply current would then be the sum of I_{CC} and I_{PP}

9. AC Characteristics for Read Operation

Symbol	Parameter	Condition	AT27C4096				Units
			-55		-90		
			Min	Max	Min	Max	
t_{ACC}[1]	Address to Output Delay	$\overline{CE}$ = $\overline{OE}$ = V_{IL}		55		90	ns
t_{CE}[1]	$\overline{CE}$ to Output Delay	$\overline{OE}$ = V_{IL}		55		90	ns
t_{OE}[1]	$\overline{OE}$ to Output Delay	$\overline{CE}$ = V_{IL}		20		35	ns
t_{DF}[1]	$\overline{OE}$ or $\overline{CE}$ High to Output Float, Whichever Occurred First			20		20	ns
t_{OH}[1]	Output Hold from Address, $\overline{CE}$ or $\overline{OE}$, Whichever Occurred First		7		0		ns

Note: 1. See the AC Waveforms for Read Operation diagram.

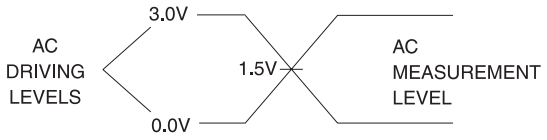
10. AC Waveforms for Read Operation[1]



Notes:
1. Timing measurement references are 0.8V and 2.0V. Input AC drive levels are 0.45V and 2.4V, unless otherwise specified.
2. $\overline{OE}$ may be delayed up to t_{CE} - t_{OE} after the falling edge of $\overline{CE}$ without impact on t_{CE}.
3. $\overline{OE}$ may be delayed up to t_{ACC} - t_{OE} after the address is valid without impact on t_{ACC}.
4. This parameter is only sampled and is not 100% tested.
5. Output float is defined as the point when data is no longer driven.

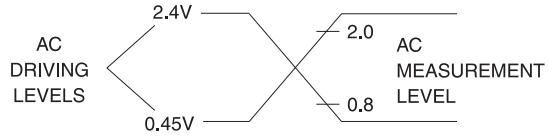
11. Input Test Waveforms and Measurement Levels

For -55 devices only:



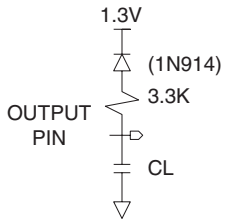
t_R, t_F < 5 ns (10% to 90%)

For -90 devices:



t_R, t_F < 20 ns (10% to 90%)

12. Output Test Load



Note: CL = 100 pF including jig capacitance.

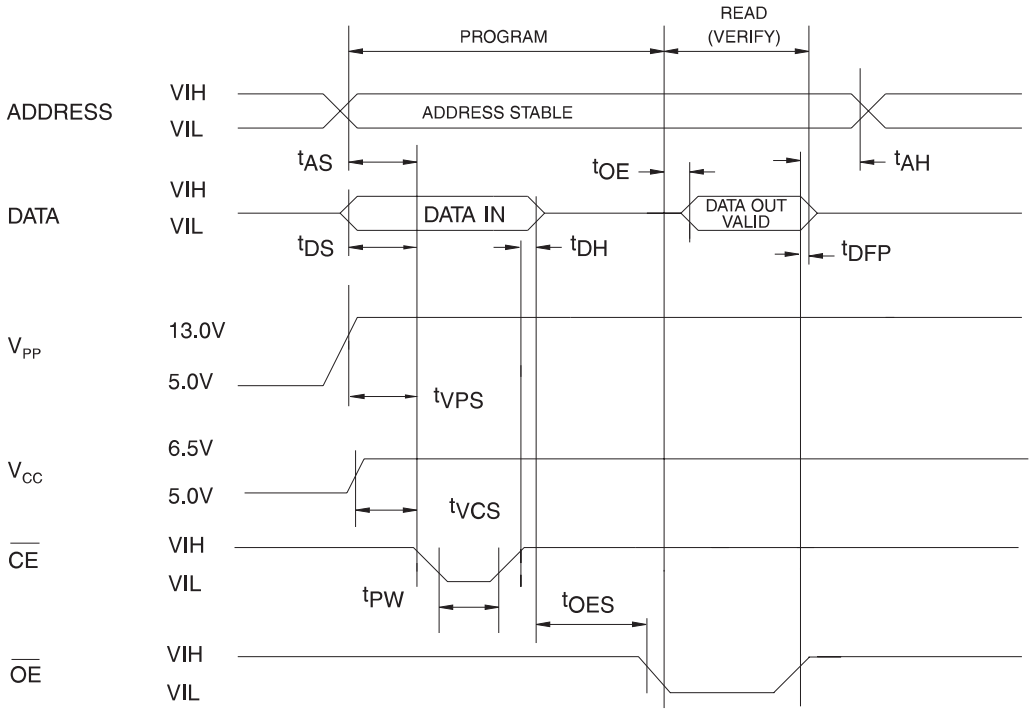
13. Pin Capacitance

f = 1 MHz, T = 25°C[1]

Symbol	Typ	Max	Units	Conditions
C_{IN}	4	10	pF	V_{IN} = 0V
C_{OUT}	8	12	pF	V_{OUT} = 0V

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.

14. Programming Waveforms[1]



Notes:
1. The Input Timing Reference is 0.8V for V_{IL} and 2.0V for V_{IH}.
2. t_{OE} and t_{DFP} are characteristics of the device but must be accommodated by the programmer.
3. When programming the AT27C4096, a 0.1 µF capacitor is required across V_{PP} and ground to suppress spurious voltage transients.

15. DC Programming Characteristics

T_A = 25 ±5°C, V_{CC} = 6.5 ±0.25V, V_{PP} = 13.0 ±0.25V

Symbol	Parameter	Test Conditions	Limits		Units
			Min	Max	
I_{LI}	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		±10	µA
V_{IL}	Input Low Level		-0.6	0.8	V
V_{IH}	Input High Level		2.0	V_{CC} + 0.7	V
V_{OL}	Output Low Voltage	I_{OL} = 2.1 mA		0.4	V
V_{OH}	Output High Voltage	I_{OH} = -400 µA	2.4		V
I_{CC2}	V_{CC} Supply Current (Program and Verify)			50	mA
I_{PP2}	V_{PP} Supply Current	$\overline{CE} = V_{IL}$		30	mA
V_{ID}	A9 Product Identification Voltage		11.5	12.5	V

16. AC Programming Characteristics

T_A = 25 ± 5°C, V_{CC} = 6.5 ± 0.25V, V_{PP} = 13.0 ±0.25V

Symbol	Parameter	Test Conditions[1]	Limits		Units
			Min	Max	
t_{AS}	Address Setup Time	Input Rise and Fall Times : (10% to 90%) 20 ns Input Pulse Levels: 0.45V to 2.4V Input Timing Reference Level: 0.8V to 2.0V Output Timing Reference Level: 0.8V to 2.0V	2		µs
t_{OES}	$\overline{OE}$ Setup Time		2		µs
t_{DS}	Data Setup Time		2		µs
t_{AH}	Address Hold Time		0		µs
t_{DH}	Data Hold Time		2		µs
t_{DFP}	$\overline{OE}$ High to Output Float Delay[2]		0	130	ns
t_{VPS}	V_{PP} Setup Time		2		µs
t_{VCS}	V_{CC} Setup Time		2		µs
t_{PW}	$\overline{CE}$ Program Pulse Width[3]		47.5	52.5	µs
t_{OE}	Data Valid from $\overline{OE}$			150	ns
t_{PRT}	V_{PP} Pulse Rise Time During Programming		50		ns

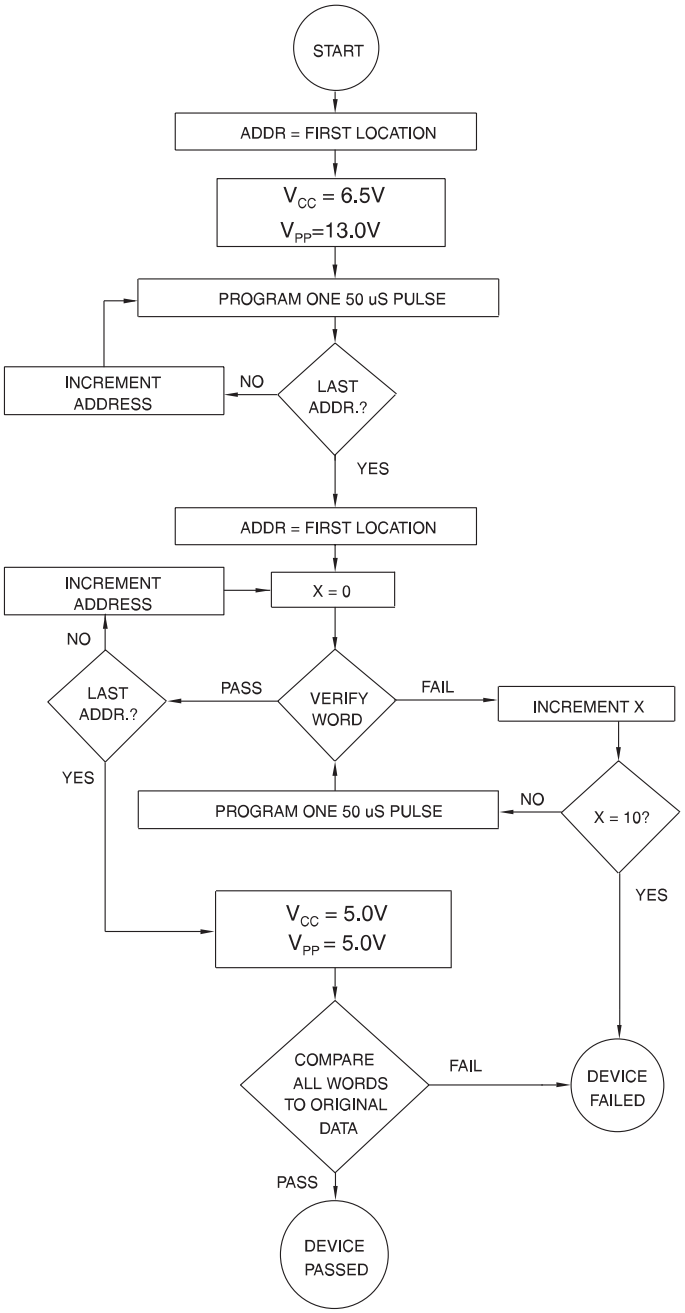
Notes:
1. V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after V_{PP}
2. This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven – see timing diagram.
3. Program Pulse width tolerance is 50 µsec ± 5%.

17. Atmel's AT27C4096 Intergrated Product Identification Code

Codes	Pins										Hex Data
	A0	O15-O8	O7	O6	O5	O4	O3	O2	O1	O0	
Manufacturer	0	0	0	0	0	1	1	1	1	0	001E
Device Type	1	0	1	1	1	1	0	1	0	0	00F4

18. Rapid Programming Algorithm

A 50 µs $\overline{CE}$ pulse width is used to program. The address is set to the first location. V_{CC} is raised to 6.5V and V_{PP} is raised to 13.0V. Each address is first programmed with one 50 µs $\overline{CE}$ pulse without verification. Then a verification/reprogramming loop is executed for each address. In the event a word fails to pass verification, up to 10 successive 50 µs pulses are applied with a verification after each pulse. If the word fails to verify after 10 pulses have been applied, the part is considered failed. After the word verifies properly, the next address is selected until all have been checked. V_{PP} is then lowered to 5.0V and V_{CC} to 5.0V. All words are read again and compared with the original data to determine if the device passes or fails.



19. Ordering Information

19.1 Standard Package

t_{ACC} (ns)	I_{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
55	40	0.1	AT27C4096-55JI AT27C4096-55PI AT27C4096-55VI	44J 40P6 40V[1]	Industrial (-40° C to 85° C)
90	40	0.1	AT27C4096-90JI AT27C4096-90PI AT27C4096-90VI	44J 40P6 40V[1]	Industrial (-40° C to 85° C)

Note: Not recommended for new designs. Use Green package option.

19.2 Green Package (Pb/Halide-free)

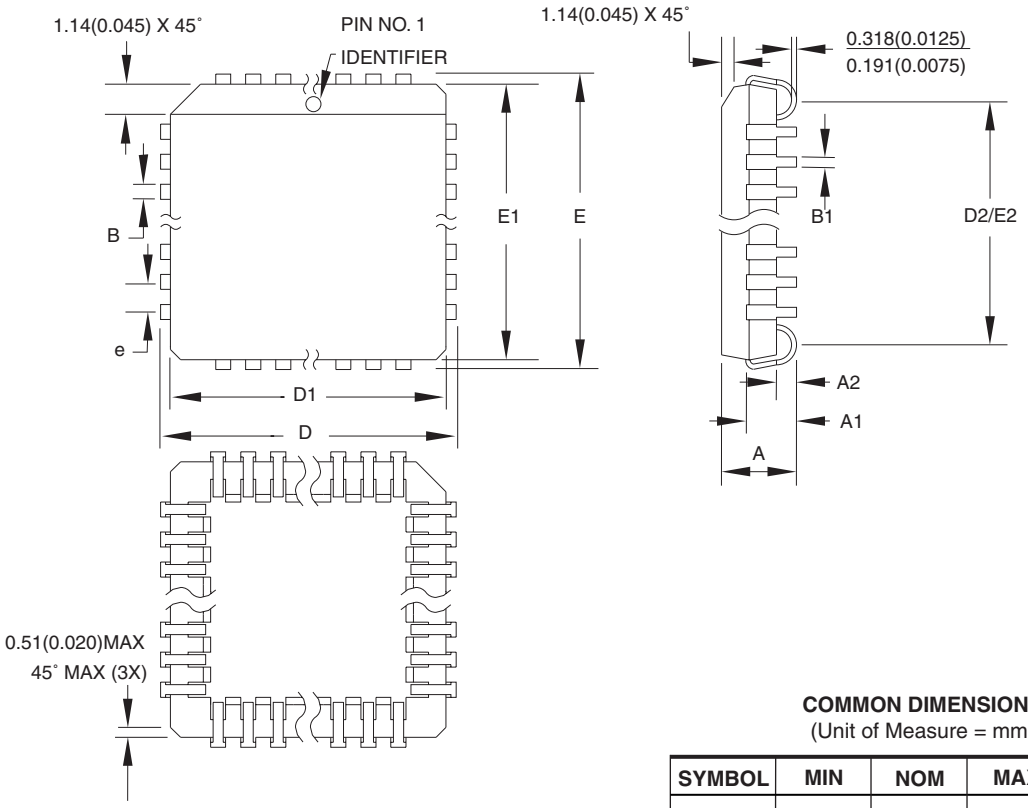
t_{ACC} (ns)	I_{CC} (mA)		Ordering Code	Package	Operation Range
	Active	Standby			
55	40	0.1	AT27C4096-55JU AT27C4096-55PU	44J 40P6	Industrial (-40° C to 85° C)
90	40	0.1	AT27C4096-90JU AT27C4096-90PU	44J 40P6	Industrial (-40° C to 85° C)

Note: 1. The 40-lead VSOP package is not recommended for new designs.

Package Type	
44J	44-lead, Plastic J-Leaded Chip Carrier (PLCC)
40P6	40-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
40V	40-lead, Plastic Thin Small Outline Package (VSOP)

20. Packaging Information

20.1 44J – PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

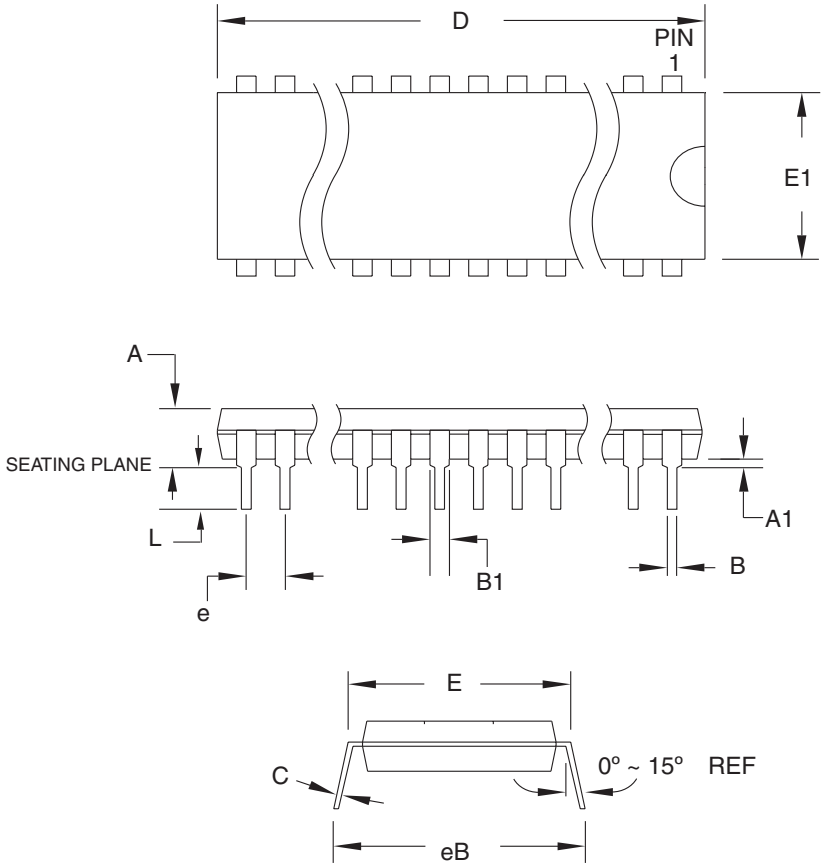
SYMBOL	MIN	NOM	MAX	NOTE
A	4.191	–	4.572	
A1	2.286	–	3.048	
A2	0.508	–	–	
D	17.399	–	17.653	
D1	16.510	–	16.662	Note 2
E	17.399	–	17.653	
E1	16.510	–	16.662	Note 2
D2/E2	14.986	–	16.002	
B	0.660	–	0.813	
B1	0.330	–	0.533	
e	1.270 TYP			

Notes:
1. This package conforms to JEDEC reference MS-018, Variation AC.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44J**, 44-lead, Plastic J-leaded Chip Carrier (PLCC)	44J	B

20.2 40P6 – PDIP



COMMON DIMENSIONS
(Unit of Measure = mm)

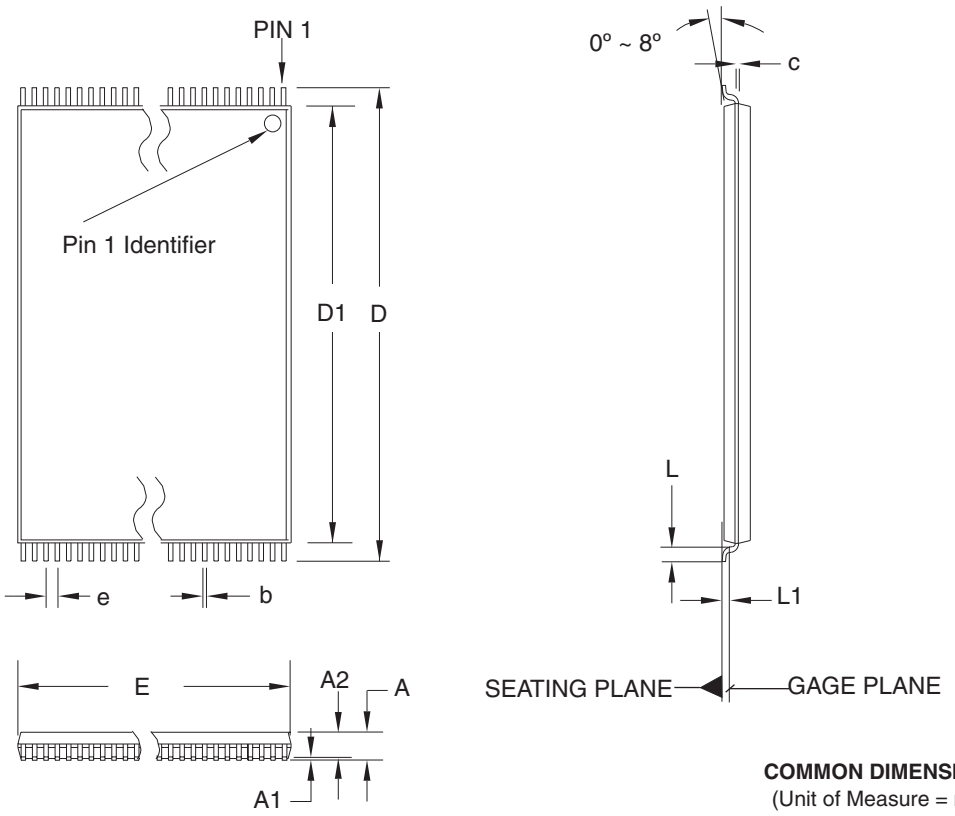
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	4.826	
A1	0.381	–	–	
D	52.070	–	52.578	Note 2
E	15.240	–	15.875	
E1	13.462	–	13.970	Note 2
B	0.356	–	0.559	
B1	1.041	–	1.651	
L	3.048	–	3.556	
C	0.203	–	0.381	
eB	15.494	–	17.526	
e	2.540 TYP			

Notes:
1. This package conforms to JEDEC reference MS-011, Variation AC.
2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

09/28/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**40P6**, 40-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)	40P6	B

20.3 40V – VSOP



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	13.80	14.00	14.20	
D1	12.30	12.40	12.50	Note 2
E	9.90	10.00	10.10	Note 2
L	0.50	0.60	0.70	
L1	0.25 BASIC			
b	0.17	0.22	0.27	
c	0.10	–	0.21	
e	0.50 BASIC			

Notes:
1. This package conforms to JEDEC reference MO-142, Variation CA.
2. Dimensions D1 and E do not include mold protrusion. Allowable protrusion on E is 0.15 mm per side and on D1 is 0.25 mm per side.
3. Lead coplanarity is 0.10 mm maximum.

10/18/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**40V**, 40-lead (10 x 14 mm Package) Plastic Thin Small Outline Package, Type I (VSOP)	40V	B

Headquarters

Atmel Corporation
2325 Orchard Parkway
San Jose, CA 95131
USA
Tel: 1(408) 441-0311
Fax: 1(408) 487-2600

International

Atmel Asia
Room 1219
Chinachem Golden Plaza
77 Mody Road Tsimshatsui
East Kowloon
Hong Kong
Tel: (852) 2721-9778
Fax: (852) 2722-1369

Atmel Europe
Le Krebs
8, Rue Jean-Pierre Timbaud
BP 309
78054 Saint-Quentin-en-
Yvelines Cedex
France
Tel: (33) 1-30-60-70-00
Fax: (33) 1-30-60-71-11

Atmel Japan
9F, Tonetsu Shinkawa Bldg.
1-24-8 Shinkawa
Chuo-ku, Tokyo 104-0033
Japan
Tel: (81) 3-3523-3551
Fax: (81) 3-3523-7581

Product Contact

Web Site
www.atmel.com

Technical Support
eprom@atmel.com

Sales Contact
www.atmel.com/contacts

Literature Requests
www.atmel.com/literature

Disclaimer: The information in this document is provided in connection with Atmel products. No license, express or implied, by estoppel or otherwise, to any intellectual property right is granted by this document or in connection with the sale of Atmel products. **EXCEPT AS SET FORTH IN ATMEL'S TERMS AND CONDITIONS OF SALE LOCATED ON ATMEL'S WEB SITE, ATMEL ASSUMES NO LIABILITY WHATSOEVER AND DISCLAIMS ANY EXPRESS, IMPLIED OR STATUTORY WARRANTY RELATING TO ITS PRODUCTS INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTY OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT. IN NO EVENT SHALL ATMEL BE LIABLE FOR ANY DIRECT, INDIRECT, CONSEQUENTIAL, PUNITIVE, SPECIAL OR INCIDENTAL DAMAGES (INCLUDING, WITHOUT LIMITATION, DAMAGES FOR LOSS OF PROFITS, BUSINESS INTERRUPTION, OR LOSS OF INFORMATION) ARISING OUT OF THE USE OR INABILITY TO USE THIS DOCUMENT, EVEN IF ATMEL HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.** Atmel makes no representations or warranties with respect to the accuracy or completeness of the contents of this document and reserves the right to make changes to specifications and product descriptions at any time without notice. Atmel does not make any commitment to update the information contained herein. Unless specifically provided otherwise, Atmel products are not suitable for, and shall not be used in, automotive applications. Atmel's products are not intended, authorized, or warranted for use as components in applications intended to support or sustain life.

© 2007 Atmel Corporation. All rights reserved. Atmel®, logo and combinations thereof, and others are registered trademarks or trademarks of Atmel Corporation or its subsidiaries. Other terms and product names may be trademarks of others.